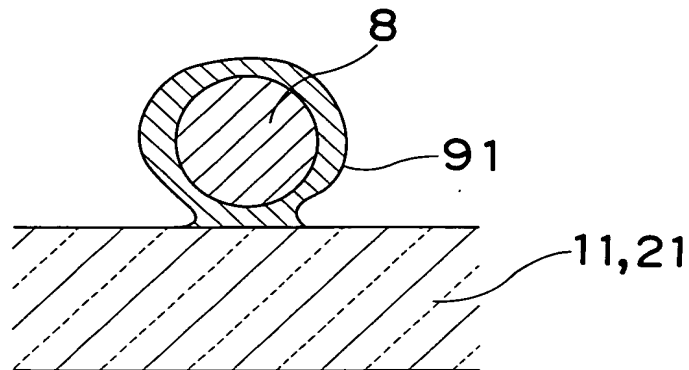
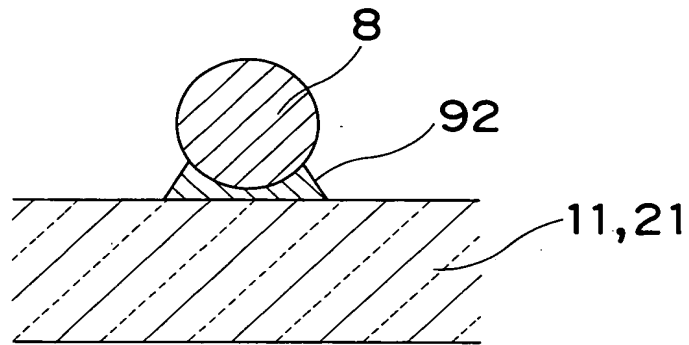
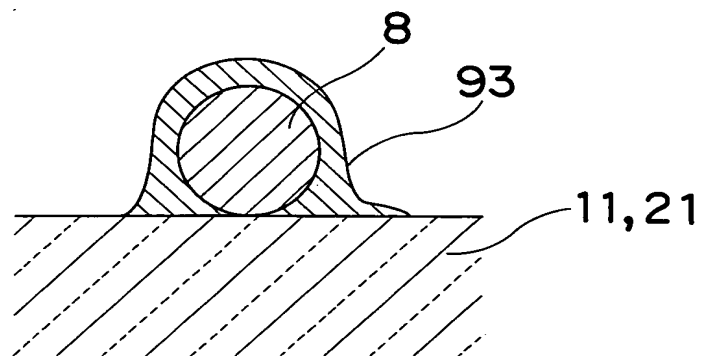


This diagram shows an exploded perspective view of a multi-layered electronic device assembly. The assembly consists of several main components:

- Top Layer (1):** A rectangular frame-like structure with a central opening. It includes a top surface (12), a bottom surface (13), and side walls (14). A central opening (15) is defined. A small protrusion (8) is located on the top surface (12).
- Middle Layer (3):** A rectangular frame-like structure with a central opening. It includes a top surface (24), a bottom surface (25), and side walls (26). A central opening (27) is defined. A small protrusion (8) is located on the top surface (24).
- Bottom Layer (2):** A rectangular frame-like structure with a central opening. It includes a top surface (21), a bottom surface (22), and side walls (23). A central opening (24) is defined. A small protrusion (8) is located on the top surface (21).
- Interlayer (4):** A thin layer located between the middle layer (3) and the bottom layer (2). It features a grid of small circular holes (4) on its top surface (21).
- Assembly (2):** The entire assembly is shown in an exploded perspective view, with arrows indicating the relative positions and assembly direction of the layers.

Other labels include 301, 302, 303, and 304, which likely refer to specific features or components of the assembly.

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*Fig. 3**Fig. 4**Fig. 5*

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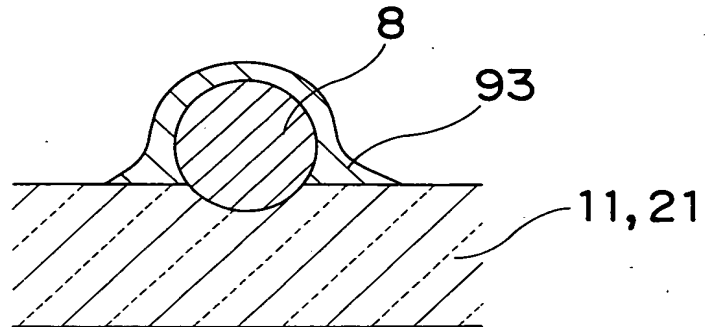
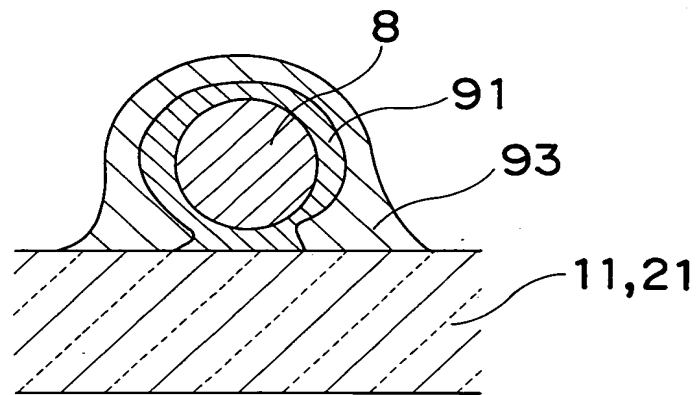
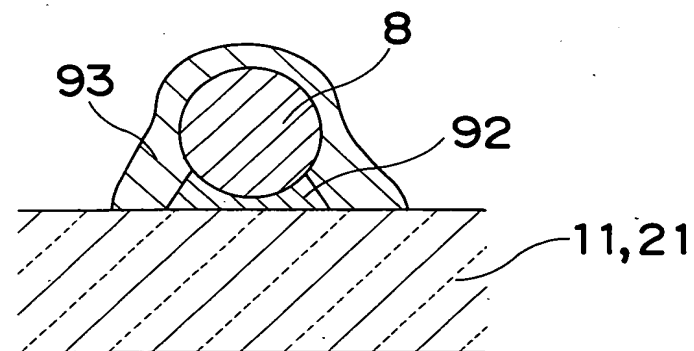
*Fig. 6**Fig. 7**Fig. 8*

Fig. 9

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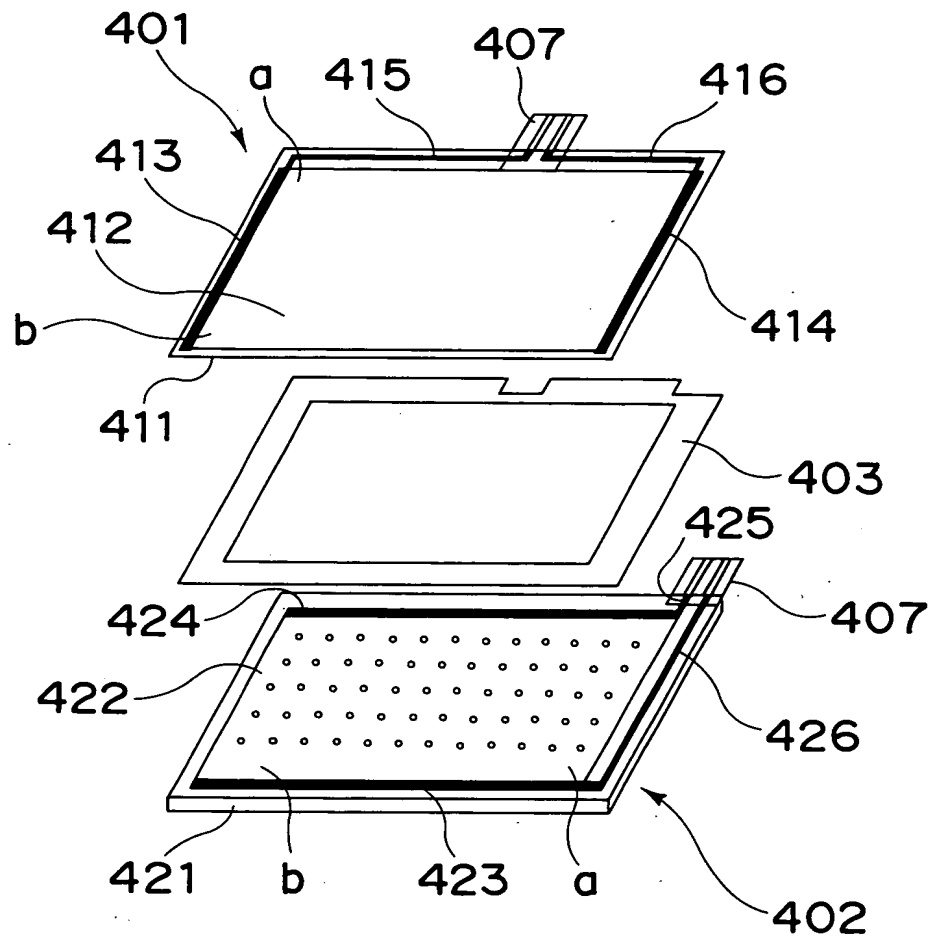


Fig. 10

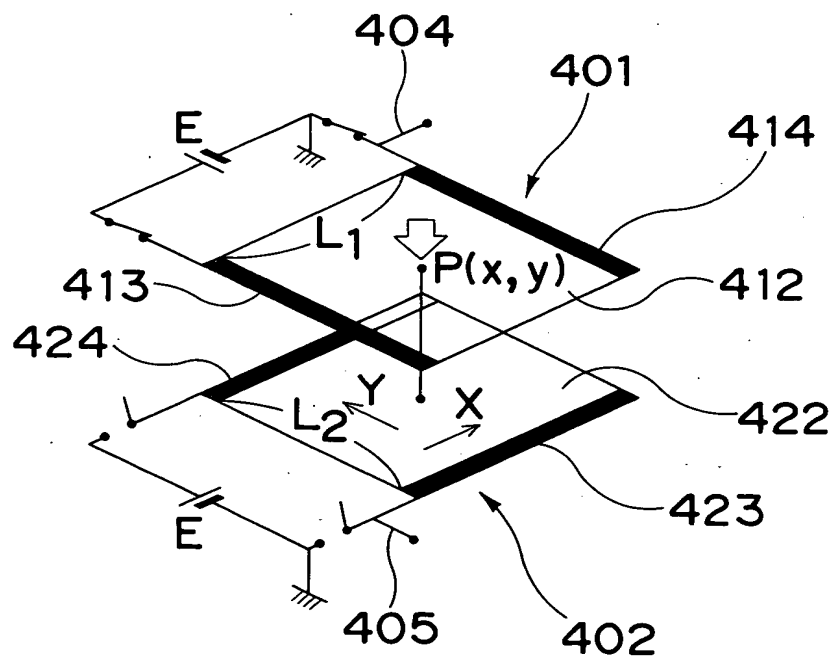


Fig. 1 1

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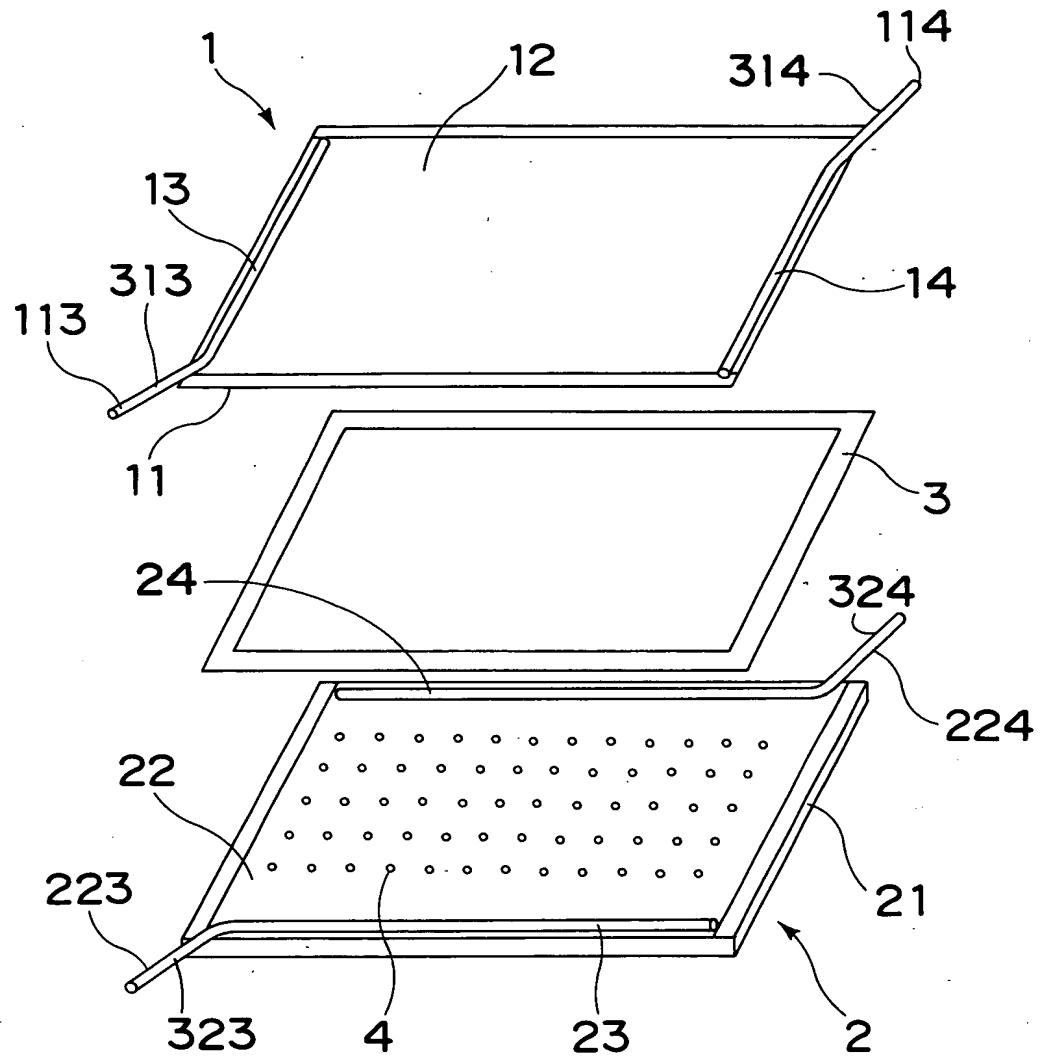
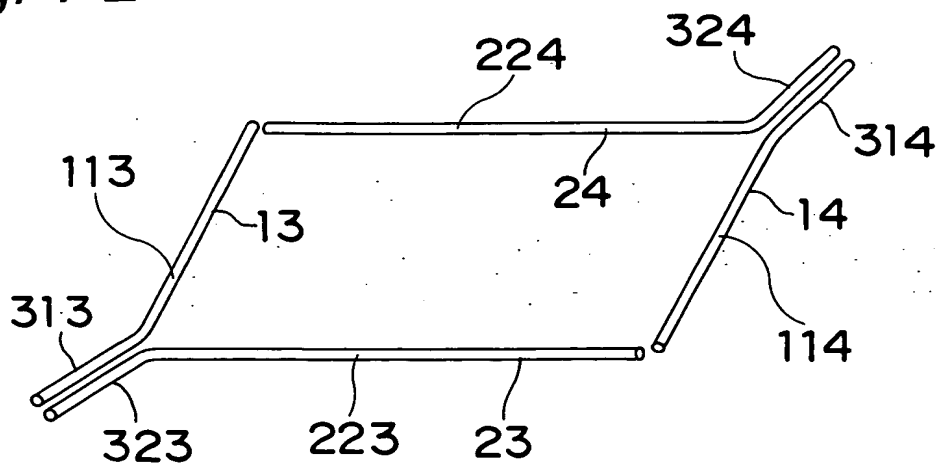


Fig. 1 2



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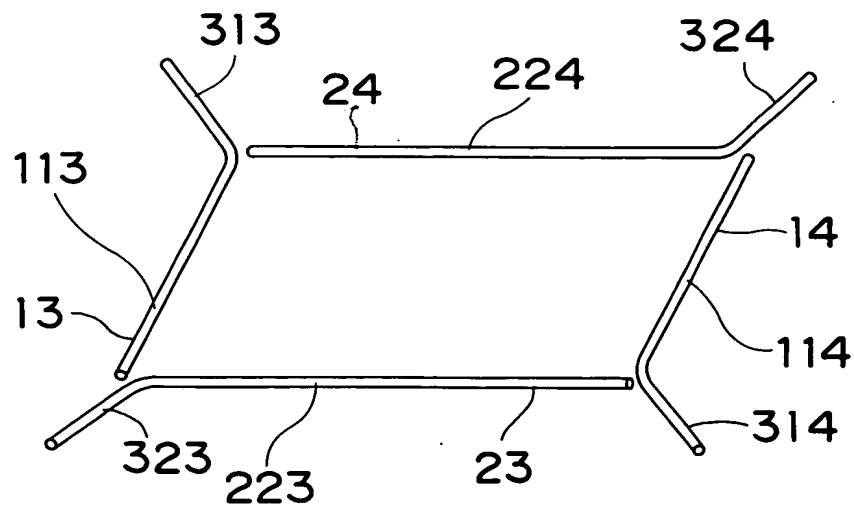
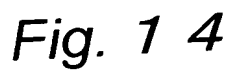


Fig. 15A

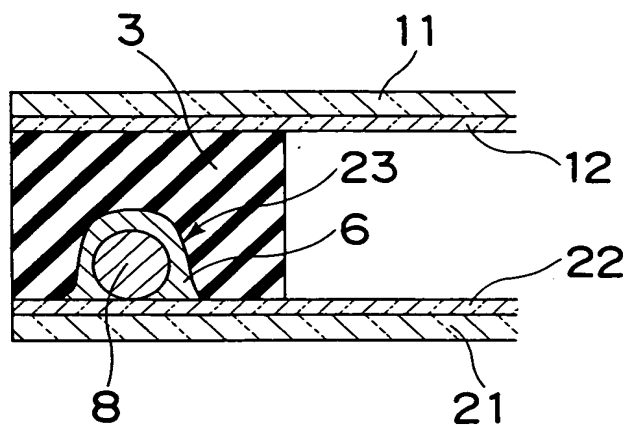


Fig. 15B

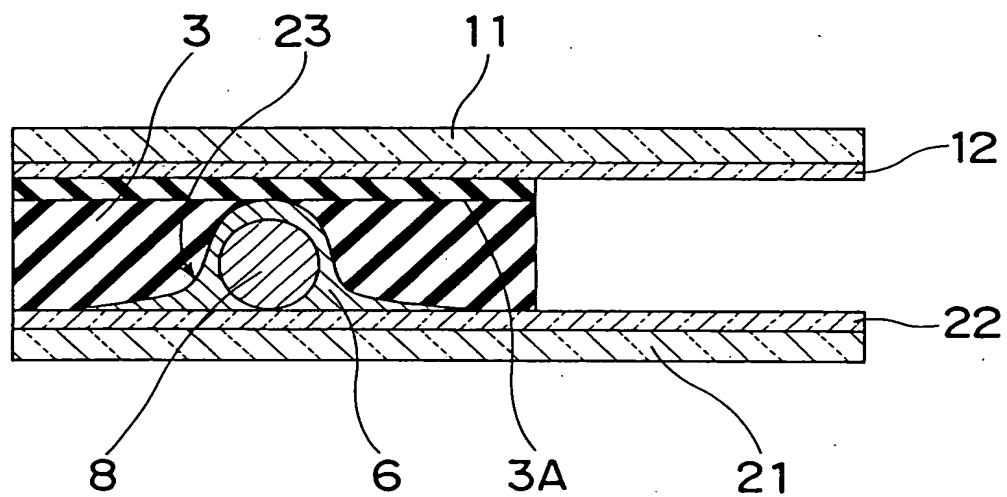
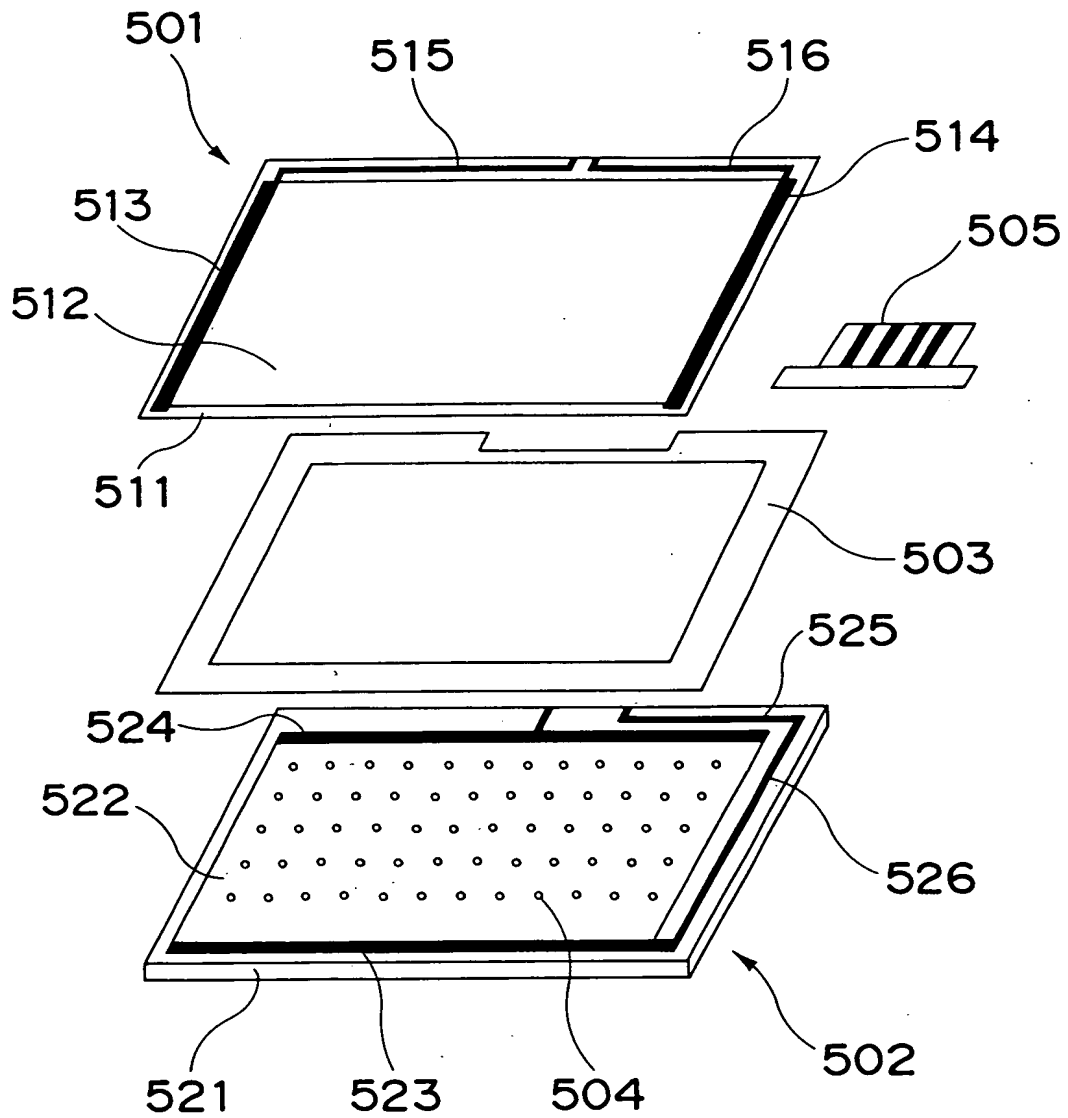


Fig. 1 6





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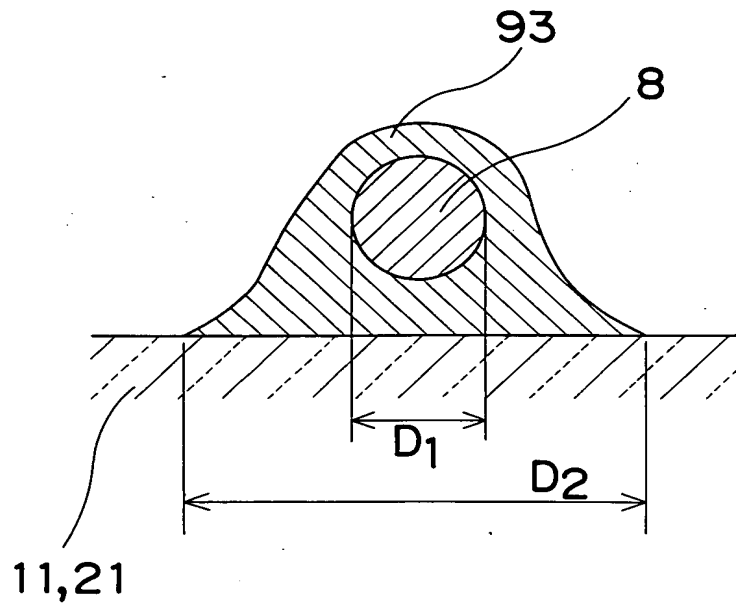
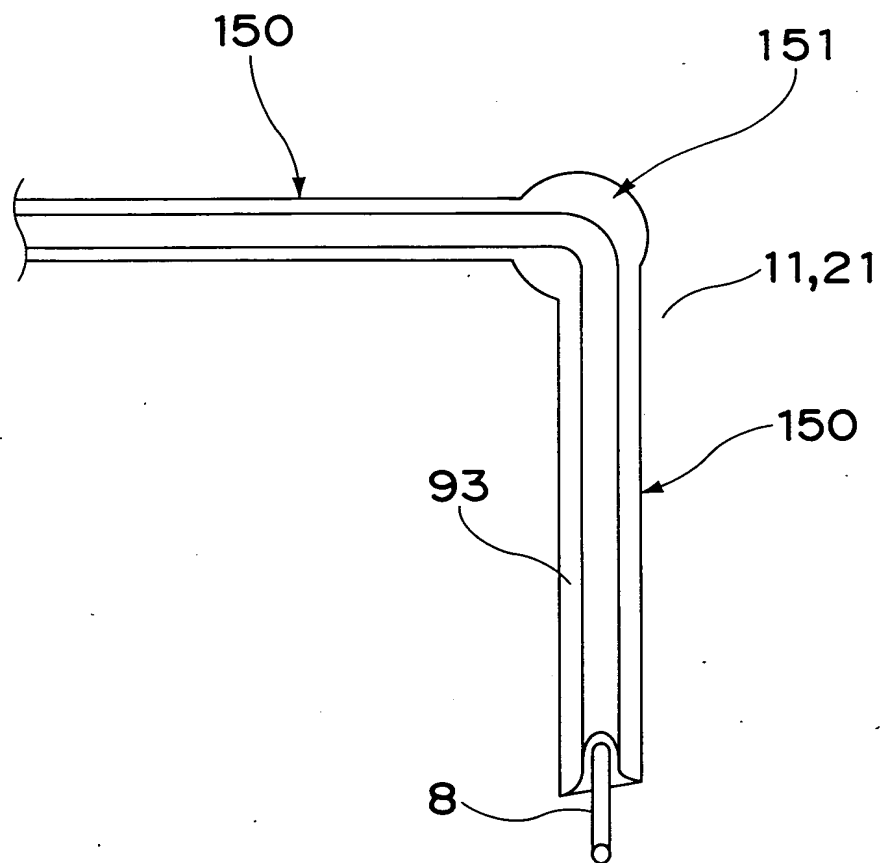
*Fig. 1 7**Fig. 1 8*

Fig. 1 9

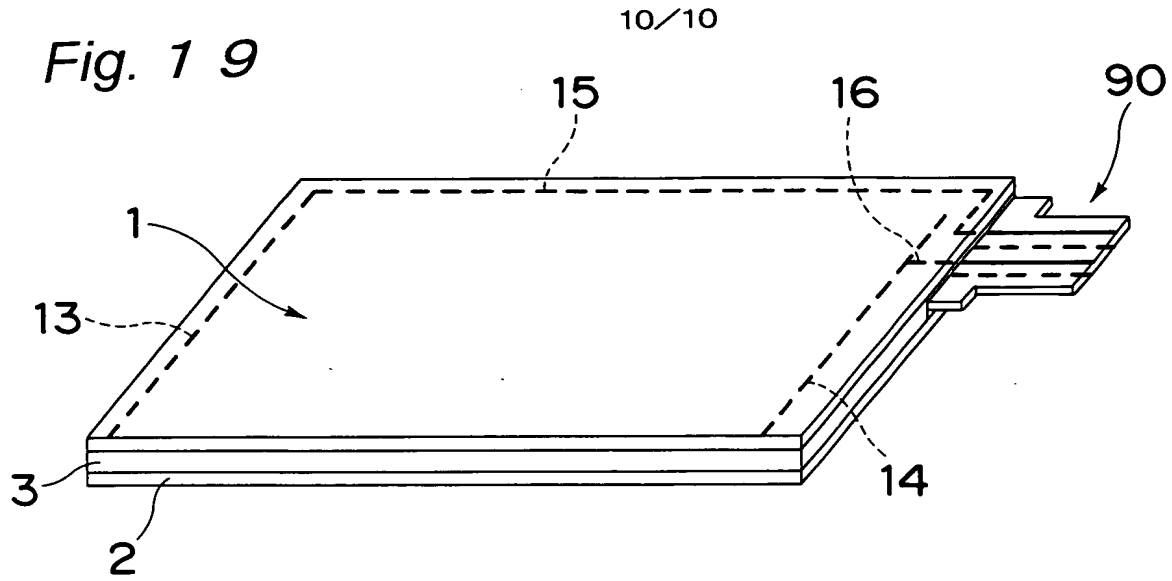


Fig. 2 0

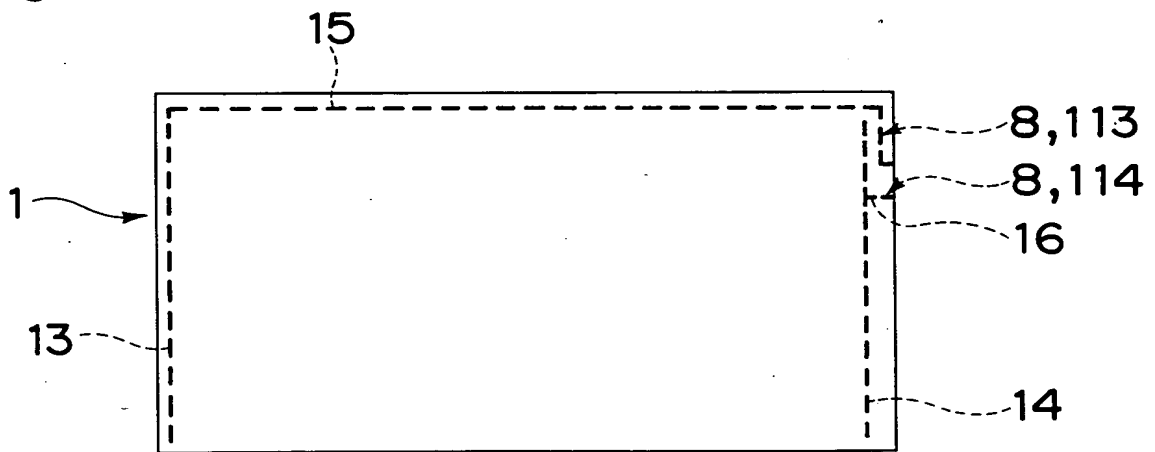


Fig. 2 1

